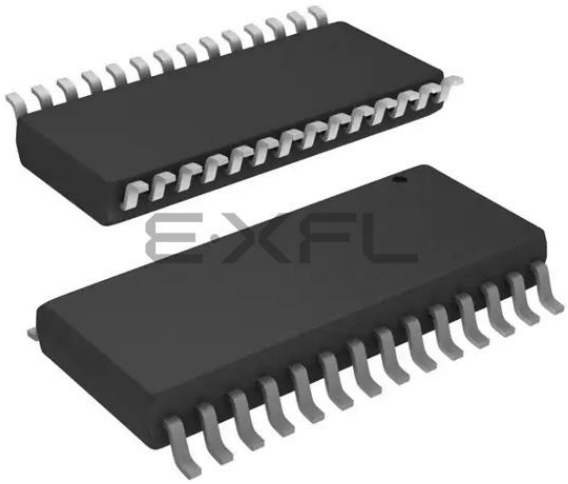


Welcome to E-XFL.COM

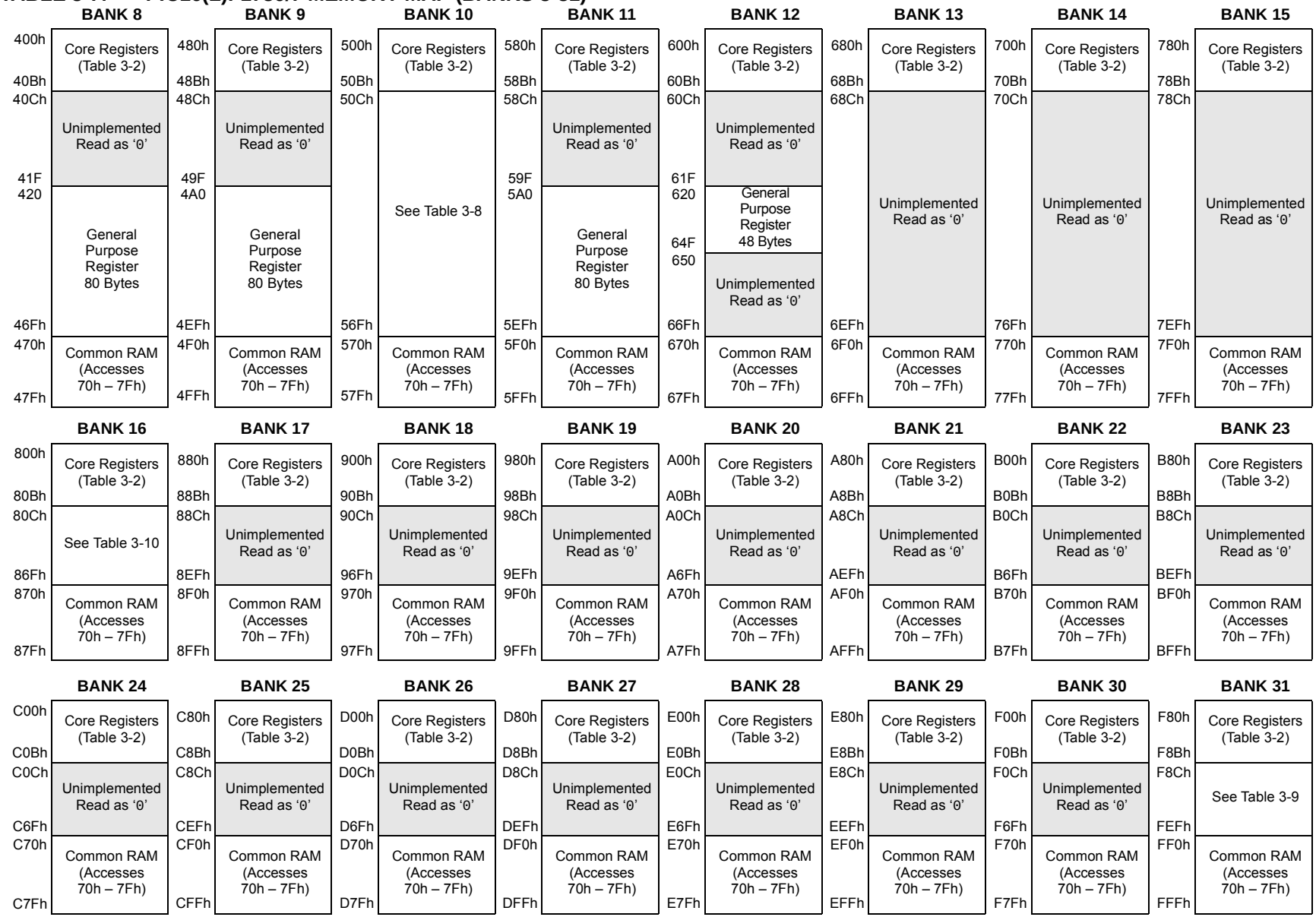
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PSMC, PWM, WDT
Number of I/O	24
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 11x12b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1786-e-so

TABLE 3-7: PIC16(L)F1786/7 MEMORY MAP (BANKS 8-31)



= Unimplemented data memory locations, read as '0'

REGISTER 4-2: CONFIG2: CONFIGURATION WORD 2

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
LVP	$\overline{\text{DEBUG}}$	$\overline{\text{LPBOR}}$	BORV	STVREN	PLLEN
bit 13					bit 8

U-1	U-1	R/P-1	U-1	U-1	U-1	R/P-1	R/P-1
—	—	$\overline{\text{VCAPEN}}$	—	—	—	WRT<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **LVP:** Low-Voltage Programming Enable bit(1)
1 = Low-voltage programming enabled
0 = High-voltage on $\overline{\text{MCLR}}$ must be used for programming

bit 12 **$\overline{\text{DEBUG}}$:** In-Circuit Debugger Mode bit(3)
1 = In-Circuit Debugger disabled, ICSPCLK and ICSPDAT are general purpose I/O pins
0 = In-Circuit Debugger enabled, ICSPCLK and ICSPDAT are dedicated to the debugger

bit 11 **$\overline{\text{LPBOR}}$:** Low-Power BOR Enable bit
1 = Low-Power Brown-out Reset is disabled
0 = Low-Power Brown-out Reset is enabled

bit 10 **BORV:** Brown-out Reset Voltage Selection bit(4)
1 = Brown-out Reset voltage (V_{BOR}), low trip point selected.
0 = Brown-out Reset voltage (V_{BOR}), high trip point selected.

bit 9 **STVREN:** Stack Overflow/Underflow Reset Enable bit
1 = Stack Overflow or Underflow will cause a Reset
0 = Stack Overflow or Underflow will not cause a Reset

bit 8 **PLLEN:** PLL Enable bit
1 = 4xPLL enabled
0 = 4xPLL disabled

bit 7-6 **Unimplemented:** Read as '1'

bit 5 **$\overline{\text{VCAPEN}}$:** Voltage Regulator Capacitor Enable bit(2)
1 = V_{CAP} functionality is disabled on RA6
0 = V_{CAP} functionality is enabled on RA6

bit 4-2 **Unimplemented:** Read as '1'

bit 1-0 **WRT<1:0>:** Flash Memory Self-Write Protection bits
4 kW Flash memory (PIC16(L)F1784 only):
11 = Write protection off
10 = 000h to 1FFh write-protected, 200h to FFFh may be modified by EECON control
01 = 000h to 7FFh write-protected, 800h to FFFh may be modified by EECON control
00 = 000h to FFFh write-protected, no addresses may be modified by EECON control
8 kW Flash memory (PIC16(L)F1786/7 only):
11 = Write protection off
10 = 0000h to 01FFh write-protected, 0200h to 1FFFh may be modified by EECON control
01 = 0000h to 0FFFh write-protected, 1000h to 1FFFh may be modified by EECON control
00 = 0000h to 1FFFh write-protected, no addresses may be modified by EECON control

Note 1: The LVP bit cannot be programmed to '0' when Programming mode is entered via LVP.
2: Not implemented on "LF" devices.
3: The $\overline{\text{DEBUG}}$ bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.
4: See V_{BOR} parameter for specific trip point voltages.

4.3 Code Protection

Code protection allows the device to be protected from unauthorized access. Program memory protection and data EEPROM protection are controlled independently. Internal access to the program memory and data EEPROM are unaffected by any code protection setting.

4.3.1 PROGRAM MEMORY PROTECTION

The entire program memory space is protected from external reads and writes by the $\overline{CP}$ bit in Configuration Words. When $\overline{CP}$ = 0, external reads and writes of program memory are inhibited and a read will return all '0's. The CPU can continue to read program memory, regardless of the protection bit settings. Writing the program memory is dependent upon the write protection setting. See **Section 4.4 "Write Protection"** for more information.

4.3.2 DATA EEPROM PROTECTION

The entire data EEPROM is protected from external reads and writes by the $\overline{CPD}$ bit. When $\overline{CPD}$ = 0, external reads and writes of data EEPROM are inhibited. The CPU can continue to read and write data EEPROM regardless of the protection bit settings.

4.4 Write Protection

Write protection allows the device to be protected from unintended self-writes. Applications, such as bootloader software, can be protected while allowing other regions of the program memory to be modified.

The WRT<1:0> bits in Configuration Words define the size of the program memory block that is protected.

4.5 User ID

Four memory locations (8000h-8003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are readable and writable during normal execution. See **Section 12.5 "User ID, Device ID and Configuration Word Access"**for more information on accessing these memory locations. For more information on checksum calculation, see the *"PIC16(L)F178X Memory Programming Specification"* (DS41457).

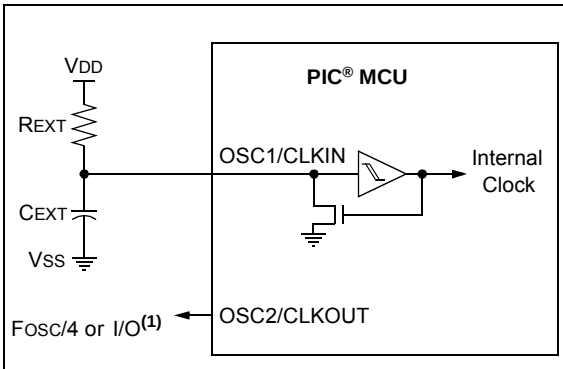
6.2.1.6 External RC Mode

The external Resistor-Capacitor (RC) modes support the use of an external RC circuit. This allows the designer maximum flexibility in frequency choice while keeping costs to a minimum when clock accuracy is not required.

The RC circuit connects to OSC1. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. The function of the OSC2/CLKOUT pin is determined by the $\overline{\text{CLKOUTEN}}$ bit in Configuration Words.

Figure 6-6 shows the external RC mode connections.

FIGURE 6-6: EXTERNAL RC MODES



Recommended values: 10 kΩ ≤ REXT ≤ 100 kΩ, <3V
3 kΩ ≤ REXT ≤ 100 kΩ, 3-5V
CEXT > 20 pF, 2-5V

Note 1: Output depends upon $\overline{\text{CLKOUTEN}}$ bit of the Configuration Words.

The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values and the operating temperature. Other factors affecting the oscillator frequency are:

- threshold voltage variation
- component tolerances
- packaging variations in capacitance

The user also needs to take into account variation due to tolerance of external RC components used.

6.2.2 INTERNAL CLOCK SOURCES

The device may be configured to use the internal oscillator block as the system clock by performing one of the following actions:

- Program the FOSC<2:0> bits in Configuration Words to select the INTOSC clock source, which will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to the internal oscillator during run-time. See **Section 6.3 "Clock Switching"**for more information.

In **INTOSC** mode, OSC1/CLKIN is available for general purpose I/O. OSC2/CLKOUT is available for general purpose I/O or CLKOUT.

The function of the OSC2/CLKOUT pin is determined by the $\overline{\text{CLKOUTEN}}$ bit in Configuration Words.

The internal oscillator block has two independent oscillators and a dedicated Phase-Lock Loop, HFPLL that can produce one of three internal system clock sources.

1. The **HFINTOSC** (High-Frequency Internal Oscillator) is factory calibrated and operates at 16 MHz. The HFINTOSC source is generated from the 500 kHz MFINTOSC source and the dedicated Phase-Lock Loop, HFPLL. The frequency of the HFINTOSC can be user-adjusted via software using the OSCTUNE register (Register 6-3).
2. The **MFINTOSC** (Medium-Frequency Internal Oscillator) is factory calibrated and operates at 500 kHz. The frequency of the MFINTOSC can be user-adjusted via software using the OSCTUNE register (Register 6-3).
3. The **LFINTOSC** (Low-Frequency Internal Oscillator) is uncalibrated and operates at 31 kHz.

6.2.2.5 Internal Oscillator Frequency Selection

The system clock speed can be selected via software using the Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register.

The output of the 16 MHz HFINTOSC, 500 kHz MFINTOSC, and 31 kHz LFINTOSC connects to a postscaler and multiplexer (see Figure 6-1). The Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register select the frequency output of the internal oscillators. One of the following frequencies can be selected via software:

- 32 MHz (requires 4x PLL)
- 16 MHz
- 8 MHz
- 4 MHz
- 2 MHz
- 1 MHz
- 500 kHz (default after Reset)
- 250 kHz
- 125 kHz
- 62.5 kHz
- 31.25 kHz
- 31 kHz (LFINTOSC)

Note:	Following any Reset, the IRCF<3:0> bits of the OSCCON register are set to '0111' and the frequency selection is set to 500 kHz. The user can modify the IRCF bits to select a different frequency.

The IRCF<3:0> bits of the OSCCON register allow duplicate selections for some frequencies. These duplicate choices can offer system design trade-offs. Lower power consumption can be obtained when changing oscillator sources for a given frequency. Faster transition times can be obtained between frequency changes that use the same oscillator source.

6.2.2.6 32 MHz Internal Oscillator Frequency Selection

The Internal Oscillator Block can be used with the 4x PLL associated with the External Oscillator Block to produce a 32 MHz internal system clock source. The following settings are required to use the 32 MHz internal clock source:

- The FOSC bits in Configuration Words must be set to use the INTOSC source as the device system clock (FOSC<2:0> = 100).
- The SCS bits in the OSCCON register must be cleared to use the clock determined by FOSC<2:0> in Configuration Words (SCS<1:0> = 00).
- The IRCF bits in the OSCCON register must be set to the 8 MHz or 16 MHz HFINTOSC set to use (IRCF<3:0> = 111x).
- The SPLLEN bit in the OSCCON register must be set to enable the 4x PLL, or the PLLEN bit of the Configuration Words must be programmed to a '1'.

Note:	When using the PLLEN bit of the Configuration Words, the 4x PLL cannot be disabled by software and the SPLLEN option will not be available.

The 4x PLL is not available for use with the internal oscillator when the SCS bits of the OSCCON register are set to '1x'. The SCS bits must be set to '00' to use the 4x PLL with the internal oscillator.

TABLE 8-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPTS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	93
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			198
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	94
PIE2	OSFIE	C2IE	C1IE	EEIE	BCL1IE	C4IE	C3IE	CCP2IE	95
PIE3	—	—	—	CCP3IE	—	—	—	—	96
PIE4	—	PSMC3TIE	PSMC2TIE	PSMC1TIE	—	PSMC3SIE	PSMC2SIE	PSMC1SIE	97
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	98
PIR2	OSFIF	C2IF	C1IF	EEIF	BCL1IF	C4IF	C3IF	CCP2IF	99
PIR3	—	—	—	CCP3IF	—	—	—	—	100
PIR4	—	PSMC3TIF	PSMC2TIF	PSMC1TIF	—	PSMC3SIF	PSMC2SIF	PSMC1SIF	101

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by interrupts.

12.7 Register Definitions: EEPROM and Flash Control

REGISTER 12-1: EEDATL: EEPROM DATA LOW BYTE REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
EEDAT<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **EEDAT<7:0>**: Read/write value for EEPROM data byte or Least Significant bits of program memory

REGISTER 12-2: EEDATH: EEPROM DATA HIGH BYTE REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	EEDAT<13:8>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **EEDAT<13:8>**: Read/write value for Most Significant bits of program memory

REGISTER 12-3: EEADRL: EEPROM ADDRESS REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
EEADR<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **EEADR<7:0>**: Specifies the Least Significant bits for program memory address or EEPROM address

REGISTER 12-4: EEADRH: EEPROM ADDRESS HIGH BYTE REGISTER

U-1	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—(1)	EEADR<14:8>						
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '1'

bit 6-0 **EEADR<14:8>**: Specifies the Most Significant bits for program memory address or EEPROM address

Note 1: Unimplemented, read as '1'.

REGISTER 13-2: APFCON2: ALTERNATE PIN FUNCTION CONTROL 2 REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0/0
—	—	—	—	—	—	—	CCP3SEL
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-1 **Unimplemented:** Read as '0'

bit 0 **CCP3SEL**: CCP3 Input/Output Pin Selection bit
1 = CCP3 is on pin RB5
PIC16(L)F1786 devices:
0 = CCP3 is on pin RC6
PIC16(L)F1784/7 devices:
0 = CCP3 is on pin RE0

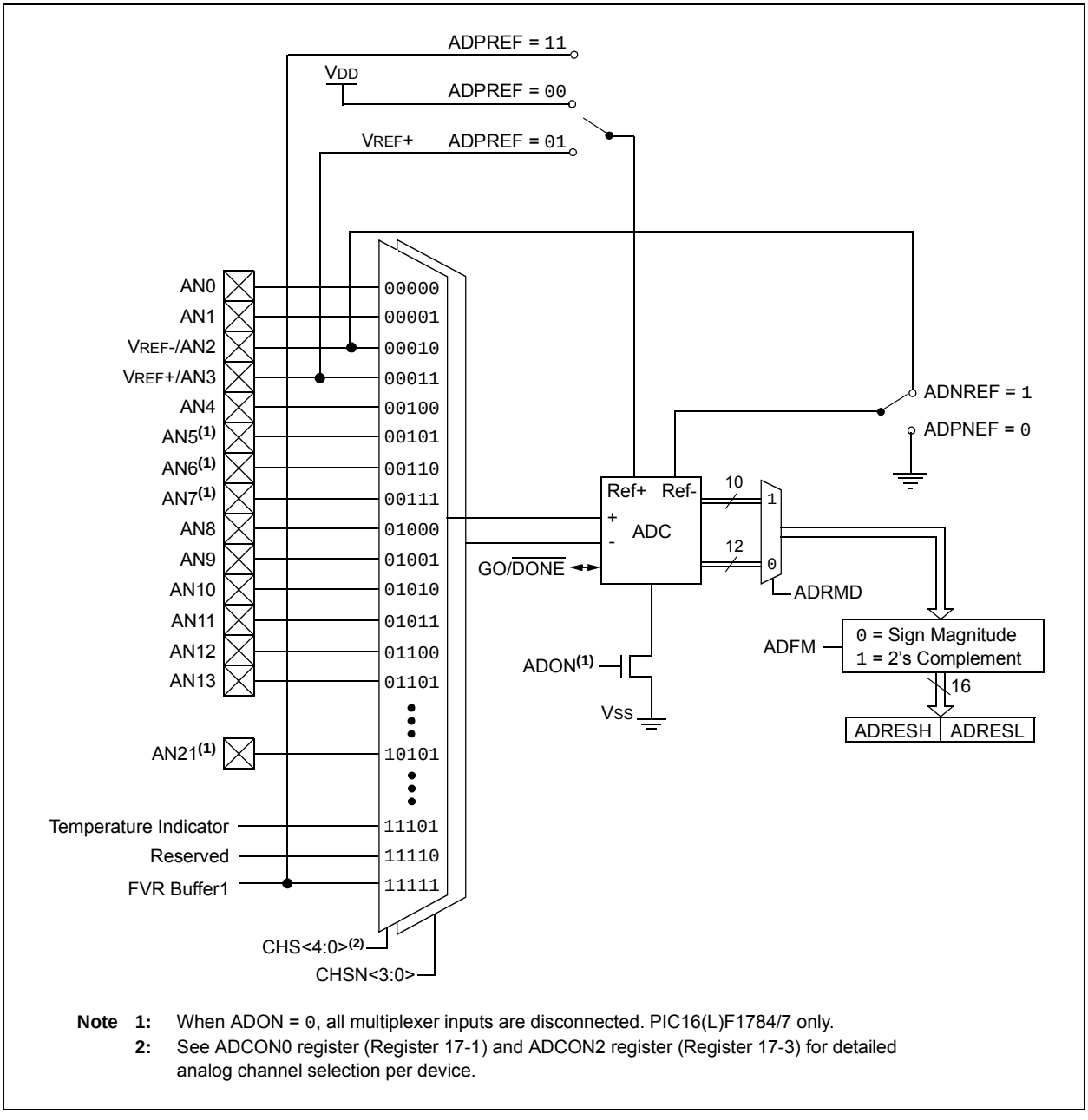
17.0 ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

The Analog-to-Digital Converter (ADC) allows conversion of a single-ended and differential analog input signals to a 12-bit binary representation of that signal. This device uses analog inputs, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a 12-bit binary result via successive approximation and stores the conversion result into the ADC result registers (ADRESH:ADRESL register pair). Figure 17-1 shows the block diagram of the ADC.

The ADC voltage reference is software selectable to be either internally generated or externally supplied.

The ADC can generate an interrupt upon completion of a conversion. This interrupt can be used to wake-up the device from Sleep.

FIGURE 17-1: ADC BLOCK DIAGRAM



Note 1: When ADON = 0, all multiplexer inputs are disconnected. PIC16(L)F1784/7 only.

2: See ADCON0 register (Register 17-1) and ADCON2 register (Register 17-3) for detailed analog channel selection per device.

REGISTER 17-2: ADCON1: ADC CONTROL REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
ADFM	ADCS<2:0>			—	ADNREF	ADPREF<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **ADFM:** ADC Result Format Select bit (see Figure 17-3)
1 = 2’s complement format.
0 = Sign-magnitude result format.

bit 6-4 **ADCS<2:0>:** ADC Conversion Clock Select bits
111 = FRC (clock supplied from a dedicated FRC oscillator)
110 = FOSC/64
101 = FOSC/16
100 = FOSC/4
011 = FRC (clock supplied from a dedicated FRC oscillator)
010 = FOSC/32
001 = FOSC/8
000 = FOSC/2

bit 3 **Unimplemented:** Read as ‘0’

bit 2 **ADNREF:** ADC Negative Voltage Reference Configuration bit
1 = VREF- is connected to external VREF- pin(1)
0 = VREF- is connected to VSS

bit 1-0 **ADPREF<1:0>:** ADC Positive Voltage Reference Configuration bits
11 = VREF+ is connected internally to FVR Buffer 1
10 = Reserved
01 = VREF+ is connected to VREF+ pin
00 = VREF+ is connected to VDD

Note 1: When selecting the FVR or VREF+ pin as the source of the positive reference, be aware that a minimum voltage specification exists. See **Section 30.0 “Electrical Specifications”** for details.

17.4 ADC Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 17-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 17-4. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an ADC acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 17-1 may be used. This equation assumes that 1/2 LSb error is used (4,096 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 17-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ *5.0V* V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(Temperature - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD}\ \text{charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD}\ \text{charge response to}\ V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) \quad ;\text{combining [1] and [2]}$$

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/8191)$$
$$= -10pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.000122)$$
$$= 1.62\mu s$$

Therefore:

$$T_{ACQ} = 2\mu s + 1.62\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.87\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: Maximum source impedance feeding the input pin should be considered so that the pin leakage does not cause a voltage divider, thereby limiting the absolute accuracy.

REGISTER 24-31: PSMCxSTR0: PSMC STEERING CONTROL REGISTER 0

bit 1 **PxSTRB**: PWM Steering PSMCxB Output Enable bit

If PxMODE<3:0> = 0000 (Single-phase PWM):
1 = Single PWM output is active on pin PSMCxOUT1
0 = Single PWM output is not active on pin PSMCxOUT1. PWM drive is in inactive state

If PxMODE<3:0> = 0001 (Complementary Single-phase PWM):
1 = Complementary PWM output is active on pin PSMCxB
0 = Complementary PWM output is not active on pin PSMCxB. PWM drive is in inactive state

IF PxMODE<3:0> = 1100 (3-phase Steering):(1)
1 = PSMCxA and PSMCxF are high. PSMCxB, PMSCxC, PSMCxD and PMSCxE are low.
0 = 3-phase output combination is not active

bit 0 **PxSTRA**: PWM Steering PSMCxA Output Enable bit

If PxMODE<3:0> = 000x (Single-phase PWM or Complementary PWM):
1 = Single PWM output is active on pin PSMCxA
0 = Single PWM output is not active on pin PSMCxA. PWM drive is in inactive state

IF PxMODE<3:0> = 1100 (3-phase Steering):(1)
1 = PSMCxA and PSMCxD are high. PSMCxB, PMSCxC, PSMCxE and PMSCxF are low.
0 = 3-phase output combination is not active

Note 1: In 3-phase Steering mode, only one PSTRx bit should be set at a time. If more than one is set, then the lowest bit number steering combination has precedence.
2: These bits are not implemented on PSMC2.

25.1 Capture Mode

The Capture mode function described in this section is available and identical for all CCP modules.

Capture mode makes use of the 16-bit Timer1 resource. When an event occurs on the CCPx pin, the 16-bit CCPRxH:CCPRxL register pair captures and stores the 16-bit value of the TMR1H:TMR1L register pair, respectively. An event is defined as one of the following and is configured by the CCPxM<3:0> bits of the CCPxCON register:

- Every falling edge
- Every rising edge
- Every 4th rising edge
- Every 16th rising edge

When a capture is made, the Interrupt Request Flag bit CCPxIF of the PIRx register is set. The interrupt flag must be cleared in software. If another capture occurs before the value in the CCPRxH, CCPRxL register pair is read, the old captured value is overwritten by the new captured value.

Figure 25-1 shows a simplified diagram of the capture operation.

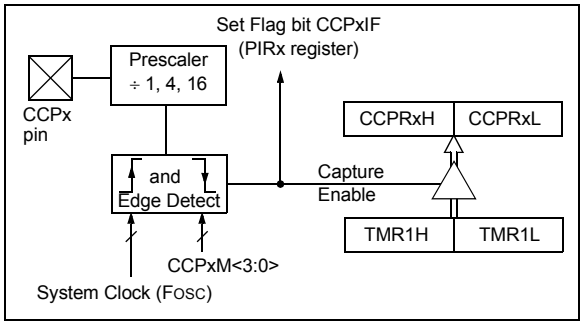
25.1.1 CCP PIN CONFIGURATION

In Capture mode, the CCPx pin should be configured as an input by setting the associated TRIS control bit.

Also, the CCP2 pin function can be moved to alternative pins using the APFCON register. Refer to **Section 13.1 "Alternate Pin Function"** for more details.

Note:	If the CCPx pin is configured as an output, a write to the port can cause a capture condition.

FIGURE 25-1: CAPTURE MODE OPERATION BLOCK DIAGRAM



25.1.2 TIMER1 MODE RESOURCE

Timer1 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work.

See **Section 22.0 "Timer1 Module with Gate Control"** for more information on configuring Timer1.

25.1.3 SOFTWARE INTERRUPT MODE

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep the CCPxIE interrupt enable bit of the PIEx register clear to avoid false interrupts. Additionally, the user should clear the CCPxIF interrupt flag bit of the PIRx register following any change in Operating mode.

Note:	Clocking Timer1 from the system clock (FOSC) should not be used in Capture mode. In order for Capture mode to recognize the trigger event on the CCPx pin, Timer1 must be clocked from the instruction clock (FOSC/4) or from an external clock source.

25.1.4 CCP PRESCALER

There are four prescaler settings specified by the CCPxM<3:0> bits of the CCPxCON register. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. Any Reset will clear the prescaler counter.

Switching from one capture prescaler to another does not clear the prescaler and may generate a false interrupt. To avoid this unexpected operation, turn the module off by clearing the CCPxCON register before changing the prescaler. Equation 25-1 demonstrates the code to perform this function.

EXAMPLE 25-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
BANKSEL CCPxCON     ;Set Bank bits to point
                    ;to CCPxCON
CLRF    CCPxCON     ;Turn CCP module off
MOVLW   NEW_CAPT_PS;Load the W reg with
                    ;the new prescaler
                    ;move value and CCP ON
MOVWF   CCPxCON     ;Load CCPxCON with this
                    ;value
```

FIGURE 26-15: I²C SLAVE, 7-BIT ADDRESS, RECEPTION (SEN = 1, AHEN = 0, DHEN = 0)

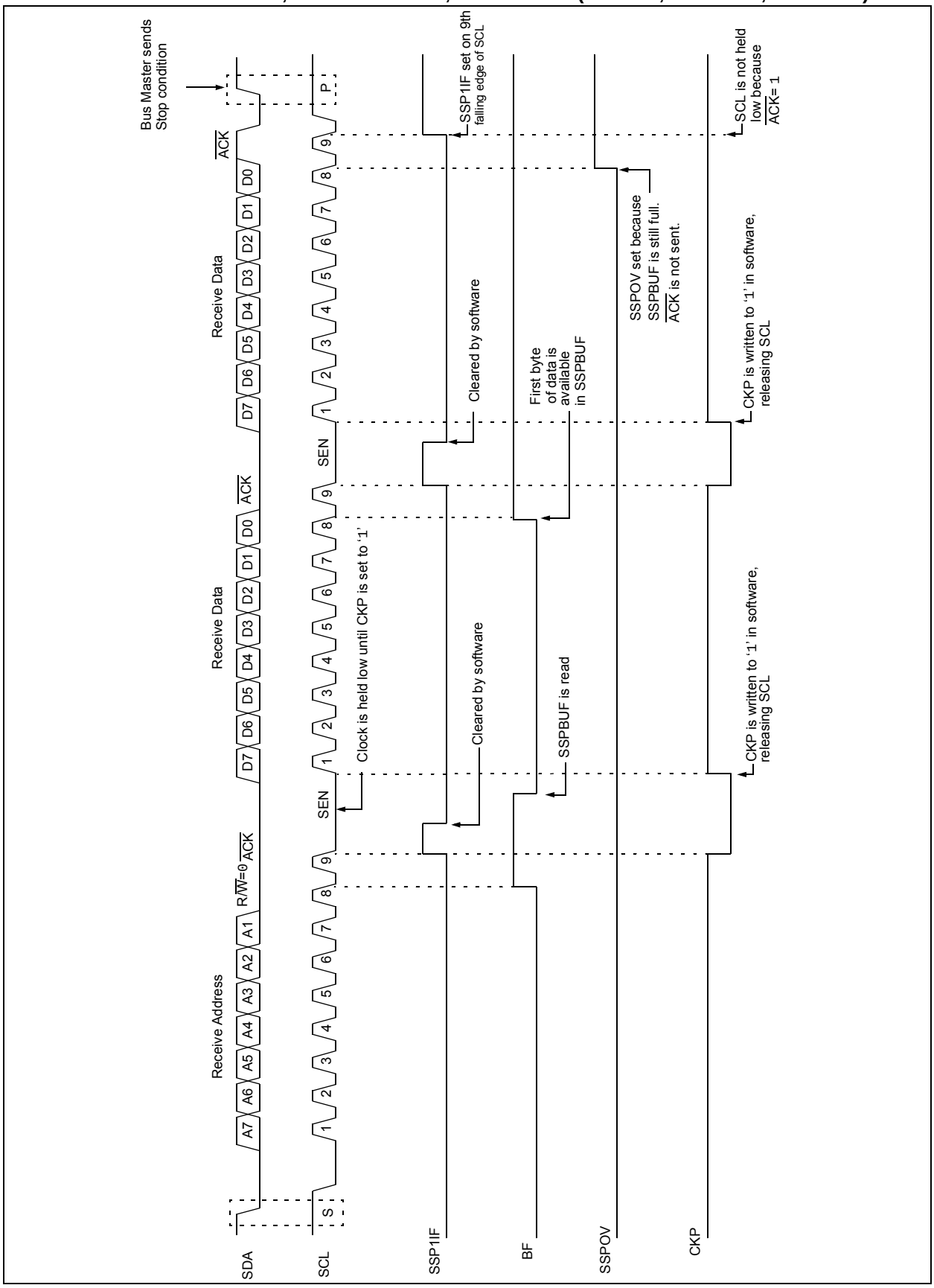
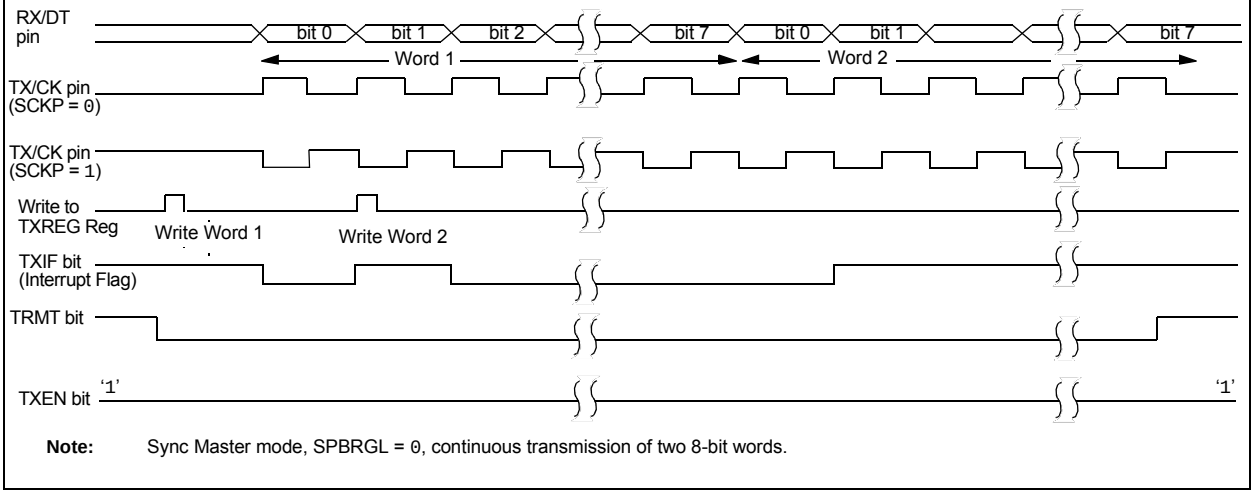


FIGURE 27-10: SYNCHRONOUS TRANSMISSION



Note: Sync Master mode, SPBRGL = 0, continuous transmission of two 8-bit words.

FIGURE 27-11: SYNCHRONOUS TRANSMISSION (THROUGH TXEN)

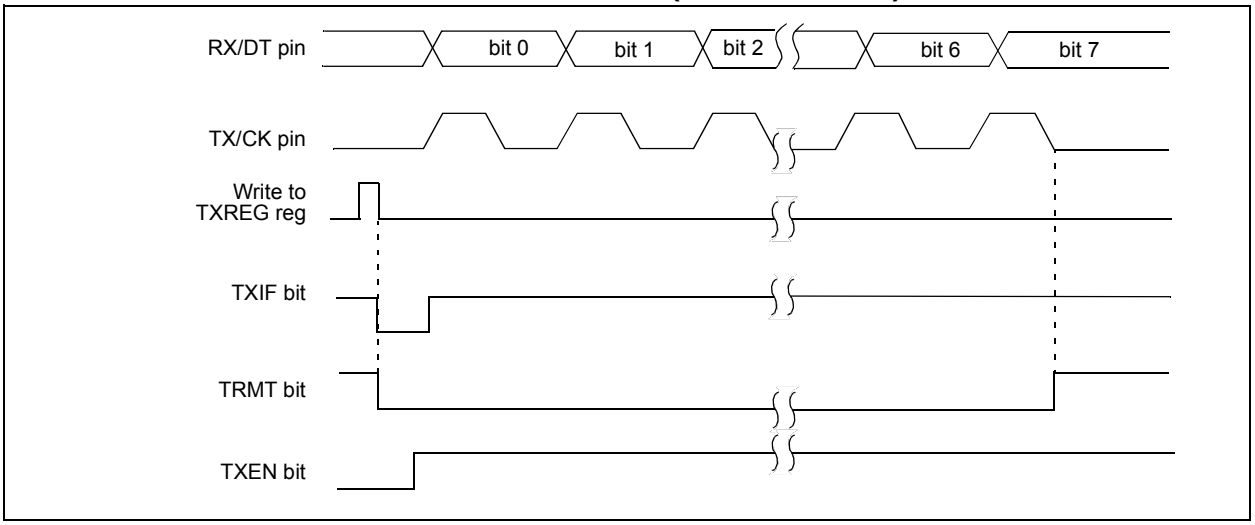


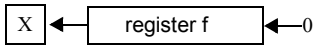
TABLE 27-7: SUMMARY OF REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON1	C2OUTSEL	CC1PSEL	SDOSEL	SCKSEL	SDISEL	TXSEL	RXSEL	CCP2SEL	127
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	347
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	93
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	94
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	98
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	346
SPBRGL	BRG<7:0>								348
SPBRGH	BRG<15:8>								348
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	142
TXREG	EUSART Transmit Data Register								337*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	345

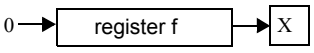
Legend: — = unimplemented location, read as '0'. Shaded cells are not used for synchronous master transmission.

* Page provides register information.

LSLF	Logical Left Shift
Syntax:	[*label*] LSLF f {,d}
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f<7>) → C (f<6:0>) → dest<7:1> 0 → dest<0>
Status Affected:	C, Z
Description:	The contents of register 'f' are shifted one bit to the left through the Carry flag. A '0' is shifted into the LSb. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.



LSRF	Logical Right Shift
Syntax:	[*label*] LSRF f {,d}
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	0 → dest<7> (f<7:1>) → dest<6:0>, (f<0>) → C,
Status Affected:	C, Z
Description:	The contents of register 'f' are shifted one bit to the right through the Carry flag. A '0' is shifted into the MSb. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.



MOVF	Move f
Syntax:	[*label*] MOVF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) → (dest)
Status Affected:	Z
Description:	The contents of register f is moved to a destination dependent upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.
Words:	1
Cycles:	1
Example:	`MOVF FSR, 0` After Instruction W = value in FSR register Z = 1

TABLE 30-2: SUPPLY VOLTAGE (I_{DD})(1,2)

PIC16LF1784/6/7			Standard Operating Conditions (unless otherwise stated)				
PIC16F1784/6/7							
Param No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D009	LDO Regulator	—	75	—	µA	—	High Power mode, normal operation
		—	15	—	µA	—	Sleep VREGCON<1> = 0
		—	0.3	—	µA	—	Sleep VREGCON<1> = 1
D010		—	8	20	µA	1.8	F_{OSC} = 32 kHz LP Oscillator mode **(Note 4)**, -40°C ≤ T_A ≤ +85°C
		—	12	24	µA	3.0	
D010		—	18	63	µA	2.3	F_{OSC} = 32 kHz LP Oscillator mode **(Note 4, 5)**, -40°C ≤ T_A ≤ +85°C
		—	20	74	µA	3.0	
		—	22	79	µA	5.0	
D012		—	160	650	µA	1.8	F_{OSC} = 4 MHz XT Oscillator mode
		—	320	1000	µA	3.0	
D012		—	260	700	µA	2.3	F_{OSC} = 4 MHz XT Oscillator mode **(Note 5)**
		—	330	1100	µA	3.0	
		—	380	1300	µA	5.0	

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through R_{EXT} is not included. The current through the resistor can be extended by the formula $I_R = V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in kΩ.

4: FVR and BOR are disabled.

5: 0.1 µF capacitor on V_{CAP}.

6: 8 MHz crystal oscillator with 4x PLL enabled.

Note: Unless otherwise noted, VIN = 5V, FOSC = 300 kHz, CIN = 0.1 µF, TA = 25°C.

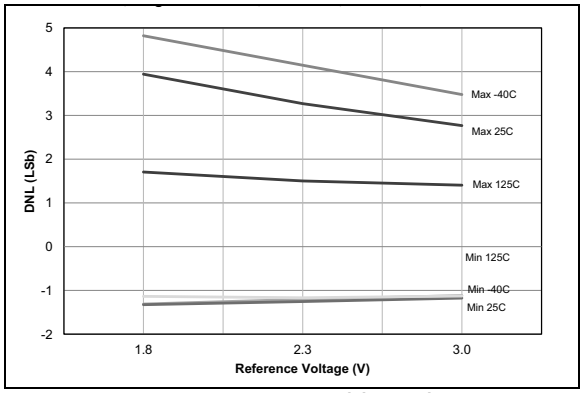


FIGURE 31-91: *ADC 12-bit Mode, Single-Ended DNL, VDD = 3.0V, TAD = 1 µS.*

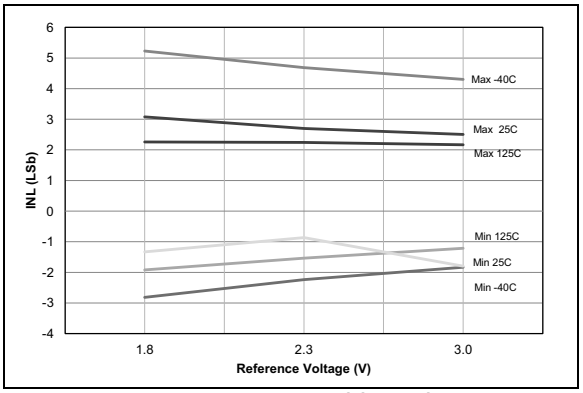


FIGURE 31-92: *ADC 12-bit Mode, Single-Ended INL, VDD = 3.0V, TAD = 1 µS.*

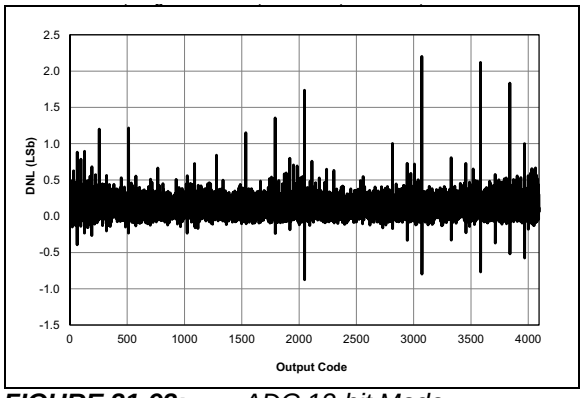


FIGURE 31-93: *ADC 12-bit Mode, Single-Ended DNL, VDD = 5.5V, TAD = 1 µS, 25°C.*

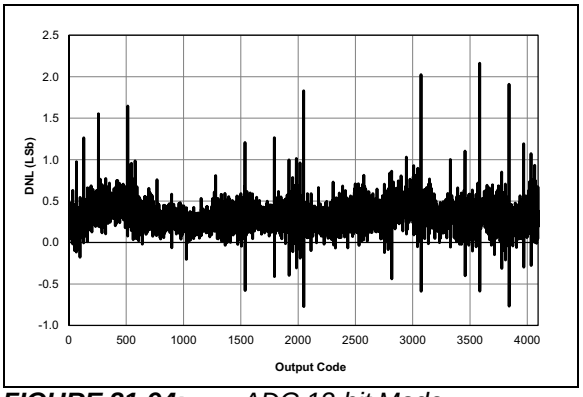


FIGURE 31-94: *ADC 12-bit Mode, Single-Ended DNL, VDD = 5.5V, TAD = 4 µS, 25°C.*

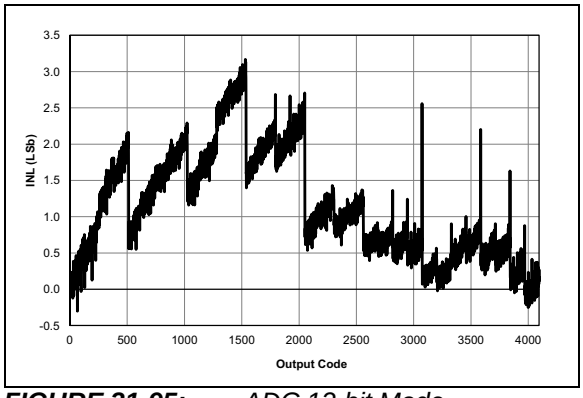


FIGURE 31-95: *ADC 12-bit Mode, Single-Ended INL, VDD = 5.5V, TAD = 1 µS, 25°C.*

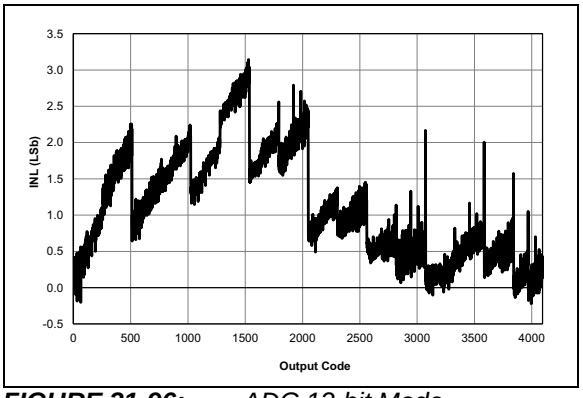
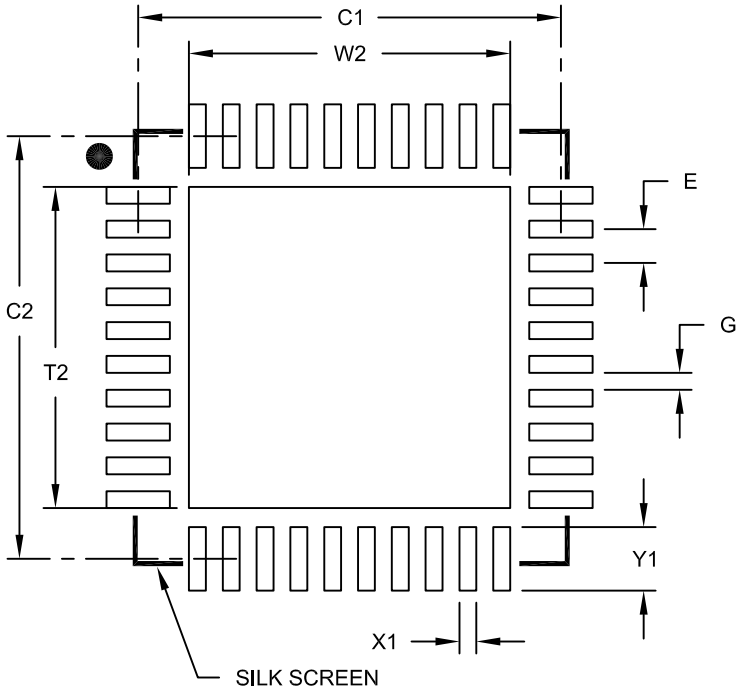


FIGURE 31-96: *ADC 12-bit Mode, Single-Ended INL, VDD = 5.5V, TAD = 4 µS, 25°C.*

40-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) - 5x5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			3.80
Optional Center Pad Length	T2			3.80
Contact Pad Spacing	C1		5.00	
Contact Pad Spacing	C2		5.00	
Contact Pad Width (X40)	X1			0.20
Contact Pad Length (X40)	Y1			0.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2156B

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com. Under "Support", click on "Customer Change Notification" and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or Field Application Engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://microchip.com/support